



APPENDIX OF CLAIMS

35. An electroplating device for wafer metallization of a wafer for interconnection comprising:

a reservoir for electrolyte,

a holder adapted to hold the wafer above said reservoir,

a counter-electrode in said reservoir,

means adapted for passing current between said counter-electrode and the wafer in said holder,

a pump adapted for pumping electrolyte from said reservoir against the wafer in said holder,

a non-conducting porous separator between said wafer holder and said counter-electrode.

36. An electroplating device for wafer metallization of a wafer for interconnection comprising:

a reservoir for electrolyte,

a holder adapted to hold the wafer above said reservoir,

a counter-electrode in said reservoir, said counter-electrode disposed concentrically with said holder,

means adapted for passing current between said counter-electrode and the wafer in said holder,

a pump adapted for pumping electrolyte from said reservoir against the water in said holder, and

Wherein the diameter of said counter-electrode is smaller than the diameter of said wafer holder.

37. An electroplating device for wafer metallization of a wafer for interconnection comprising:

a reservoir for electrolyte,

a holder adapted to hold the wafer above said reservoir,

a counter-electrode in said reservoir,

means adapted for passing current between said counter-electrode and the wafer in said holder,

a pump adapted for pumping electrolyte from said reservoir against the wafer in said holder, and

means for applying current to said pump during the electroplating process.

38. An electroplating device of wafers for interconnection comprising:

a reservoir for electrolyte,

a holder adapted to hold a wafer above said reservoir,

a counter-electrode in said reservoir,

means for passing current between said counter-electrode and a wafer in said holder,

a pump for pumping electrolyte from said reservoir against said wafer,

and

a distributor positioned in said reservoir including a disk having a plurality of holes adapted to provide a flow of electrolyte through the disk that is uniform along a radius of the disk.

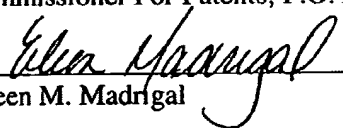


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